IX - PUBLICATIONS

Books and magazines are authorized by the member of CMP.

Books and magazines

2011

COURTOIS B.
Published by John Wiley & Sons
To appear in 2011

DI PENDINA G.
Chapter in the book "Advances in Engineering Research"
Published by Nova Science Publishers, Inc.
To appear in 2011

2010

COURTOIS B., RENCZ M.*, Editors
Proceedings of 16th International Workshop on THERmal Investigations of ICs and Systems (THERMINIC’10), ISBN 978-2-35500-012-6, Barcelona, Spain, 6-8 October 2010
* Budapest University of Technology and Economics, Hungary

COURTOIS B. et al, Editors

BEN-TEKAYA R., BAGANNE A., TORKI K., TOURKI R.
Performance evaluation of MiC@R NoC for real-time Applications, International Journal of Computer Aided Engineering and Technology 2010 - Vol. 2, No.2/3, pp. 274 – 293

MACHHOUT M., GUITOUNI Z., TORKI K., KHRIJI L., TOURKI R.
Coupled FPGA/ASIC implementation of elliptic curve cryptoprocessor, International Journal of Network Security & Its Applications (IJNSA), Volume 2, Number 2, April 2010

2009

COURTOIS B., RENCZ M.*, Editors
* Budapest University of Technology and Economics, Hungary

COURTOIS B., Guest Editor

COURTOIS B., DE VENUTO D.* Guest Editors
* Politecnico di Bari, Italy

COURTOIS B. et al, Editors
COURTOIS B., Guest Editor
Special Issue on selected papers on Symposium on Design, Test, Integration and Packaging of MEMS/ MOEMS (DTIP 2006)
An International Journal on Analogue Integrated Circuits and Signal Processing

2006

COURTOIS B., MARKUS K.* et al., Editors
Proceedings of Symposium on Design, Test, Integration and Packaging of MEMS/ MOEMS (DTIP 2006),
Stresa, Italy, 26-28 April 2006

COURTOIS B., RENCZ M.*, LASANCE C.**, SZEKELY V.***, Editors
Proceedings of 12th International Workshop on THERmal Investigations of ICs and Systems
(THERMINIC'06), Nice, Côte d’Azur, France, September 27–29, 2006

* MicRed Microelectronics Res & Dev Ltd., Hungary; ** Philips, The Netherlands; *** Budapest University of Technology and Economics, Hungary

SHAKOURI A.*, KANG S.M.*, BAR-COHEN A.**, COURTOIS B., Guest Editors
Scanning the Special Issue on On-Chip thermal engineering
Proceedings of the IEEE, Vol.94, No.8, pp. 1-3, August 2006

* University of California Santa Cruz, USA; ** University of Maryland, College Park, USA

COURTOIS B., Michel B.*, Editorial
Special Issue on the Symposium on Design, Test, Integration of MEMS/MOEMS (DTIP'05)

* IZM, Berlin, Germany

COURTOIS B., Guest Editor
Special Issue on selected papers on Symposium on Design, Test, Integration and Packaging of MEMS/ MOEMS (DTIP 2005)
An International Journal on Analogue Integrated Circuits and Signal Processing

2005

COURTOIS B., MARKUS K.* et al., Editors
Proceedings of Symposium on Design, Test, Integration and Packaging of MEMS/ MOEMS (DTIP 2005),
Montreux, Switzerland, June 1-3, 2005

COURTOIS B., RENCZ M.*, LASANCE C.**, SZEKELY V.***, Editors
Proceedings of 11th International Workshop on THERmal Investigations of ICs and Systems
(THERMINIC'05), Belgirate, Lake Maggiore, Italy, September 27–30, 2005

* MicRed Microelectronics Res & Dev Ltd., Hungary; ** Philips, The Netherlands; *** Budapest University of Technology and Economics, Hungary

COURTOIS B., Guest Editor
Special issue on European Micro and Nano Systems (EMN04) held in Paris, 20–21 October, 2004

COURTOIS B., Guest Editor
Special Issue on selected papers on Symposium on Design, Test, Integration and Packaging of
MEMS/ MOEMS (DTIP 2004)

DE VENUTO D.*, COURTOIS B., Editors
Proceedings of 1st International Workshop on Advances in Sensors and Interfaces (IWASI'05), Bari, Italy,
* Politecnino di Bari, Italy

ROMAN C., CIONTU F., COURTOIS B.
Nanoscopic modeling of a carbon nanotube force-measuring biosensors

Conferences and Workshops

2011

COURTOIS B.
Electronics for Energy Management
Keynote at ASQED 2011, July 19-20 2011, Kuala Lumpur, Malaysia

2010

COURTOIS B.
Electronics for energy management
Keynote at 5th International Design & Test Workshop (IDT), December 14-16, 2010, Abu Dhabi, UAE

COURTOIS B.
Electronics and sensors for biomed applications
IEEE SENSORS 2010 Conference, November 1 - 4, 2010, Waikoloa, USA

TORKI K.
CMP service for 3D-IC: Design Methodologies & Manufacturing
Invited paper at TWEPP-10, Topical Workshop Electronics for Particle Physics, 20-24 September 2010, Aachen, Germany

COURTOIS B.
Infrastructure for ICs and MEMS manufacturing
IEEE/ASME International Conference on Mechatronic and Embedded Systems and Applications (MESA)
July 15-17, 2010, Qingdao, ShanDong, China

COURTOIS B.
And now, where do we go?
Keynote at 8th European Workshop on Microelectronics Education (EWME), May 10-12, 2010, Darmstadt, Germany

COURTOIS B.
Energy management: how electronics can help?
International Multi-Conference on Complexity, Informatics and Cybernetics (IMCIC), April 6-9 2010, Orlando, USA

COURTOIS B.
ICs and MEMS for energy management
Keynote at 11th IEEE Latin-American Test Workshop (LATW), March 28-31 2010, Punta del Este, Uruguay

COURTOIS B.
Gestion de l'énergie par les composants
Invited speaker at Journée d'étude « Les SEC se mettent au vert »
March 4 2010 – Université Paul Sabatier, Toulouse, France

2009

COURTOIS B.
CMP Service: BioMed applications
12th International Symposium on Integrated Circuits (ISIC), December 14-16 2009, Singapore

COURTOIS B.
SOC/SIP for energy management
*Invited paper*, International SoC Design Conference (ISOCC), November 22-24 2009, Busan, Korea

DHAHRI S., KABBAI L., ZITOUNI A., TORKI K., TOURKI R.
A low power ASIC design of a FSS motion estimator for H.264AVC
Humboldt Kolleg, Advancements in Nanotechnology and Microelectronics (ANM’09), November 13-14, 2009, Tunisia

COURTOIS B., TORKI K., DUMONT S., EYRAUD S., PAILLOTIN J-F, DI PENDINA G.
Infrastructures for Education and Research: from National Initiatives to global operations
The 13th World Multi-Conference on Systemics, Cybernetics and Informatics (WMSCI), July 10-13 2009, Orlando, USA

COURTOIS B.
Prototyping custom circuits and systems: 20 years back, X years forward.
*Keynote* in 20th IEEE/IFIP International Symposium on Rapid System Prototyping (RSP’09), June 22-26 2009, Paris, France

COURTOIS B.
Infrastructures for Education and Research: from National initiatives to global operations and from EE&CS communities to other communities and key applications
*Keynote* in 4th IEEE International Conference on Design & Technology of Integrated Systems in Nanoscale Era (DTIS), April 6-7 2009, Cairo, Egypt

BEN-TEKAYA R., BAGANNE A., TORKI K., TOURKI R.
Performance Evaluation of MIC@R NoC for Real-Time applications
4th IEEE International Conference on Design & Technology of Integrated Systems in Nanoscale Era (DTIS), April 6-7 2009, Cairo, Egypt

NICOLAIDIS M., TORKI K., NATALI F., BELHADDAD K., ALEXANDRESCU D.
Implementation and Validation of a Low-Cost Single-EventLatchup Mitigation Scheme

COURTOIS B.
CMP Service: past, present, future
*Invited paper* in 15th Workshop on Synthesis and System Integration of Mixed Information technologies (SASIMI), March 9-10 2009, Okinawa, Japan

COURTOIS B.
Infrastructures services like CMP: where should they be heading?
*Invited talk* in CMOS Emerging Technologies Workshop, February 18-20 2009, Banff, Canada

COURTOIS B., TORKI K., DUMONT S., EYRAUD S., PAILLOTIN J-F, DI PENDINA G.
Infrastructures for Education, Research and Industry in Microelectronics - a look worldwide and a look at India
22nd International Conference on VLSI Design, 5-9 January 2009, New-Delhi, India

2008

COURTOIS B.
Integrated Circuit Brokers: Where do they come from? Where are they heading?
*Keynote* in IEEE International Conference on Microelectronics (ICM’08), December 14-17, 2008 in Sharjah, UAE

BEN-TEKAYA R., BAGANNE A., TORKI K., TOURKI R.
Performance Evaluation of MIC@R Router for On-Chip Networks
IDT’08, December 20-22 2008, Monastir, Tunisia

GUESMI H., DJEMAL R., TORKI K., TOURKI R.
Design of a High Active Queue management
9e Colloque Africain sur la Recherche en Informatique et en Mathématiques Appliquées 27-30 Octobre 2008, Rabat, Morocco
COURTOIS B., CHARLOT B.*, DI PENDINA G., RUFER L.**
Electronics Manufacturing Infrastructures for Education and Commercialization
*IES/MITEA, Montpellier – France, **TIMA, Grenoble – France

COURTOIS B., CHARLOT B.*, DI PENDINA G., RUFER L.**
Infrastructures for Education, Research and Industry: CMOS and MEMS for BioMed
Invited paper at the 12th World Multi-Conference on Systemics, Cybernetics and Informatics (WMSCI 2008), Orlando USA, 29 June – 2 July 2008
*IES/MITEA, Montpellier - France, **TIMA, Grenoble – France

COURTOIS B., CHARLOT B.*, DI PENDINA G., RUFER L.**
Infrastructures for mixed signalS in biology and medicine
14th IEEE International Mixed-Signals, sensors, and systems Test Workshop (IMS3TW 2008), Vancouver, Canada, 18-20 June 2008
*IES/MITEA, Montpellier - France

COURTOIS B., EYRAUD S., PAILLOTIN J-F, DI PENDINA G., TORKI K.
Infrastructures for Education, Research and Industry in Microelectronics
7th European Workshop on Microelectronics Education (EWME 2008), Budapest (Hungary) 28-30 May 2008

COURTOIS B.
Infrastructures for Education, Research and Industry in ICs and MEMS

COURTOIS B, TORKI K., DUMONT S., EYRAUD S., PAILLOTIN J-F., DI PENDINA G.
Infrastructures for Education, Research and Industry in Microelectronics
14th IEEE Mediterranean Electrotechnical Conference (MELECON 2008), Ajaccio (France), 5-7 May 2008.

2007

TORKI K.
CMP, Infrastructures for Microelectronics & MEMS

COURTOIS B., TORKI K., COLIN S., DELORI H., EYRAUD S., PAILLOTIN J.-F., DI PENDINA G., DUMONT S.
Infrastructures for Education, Research and Industry in Microelectronics – Recent Developments.

BHAR J., OUNI R., TORKI K., NASRI S.
Handover Strategies Challenges in Wireless ATM Networks
World Academy of Science, Engineering and Technology, April 2007, ISSN 1307-6884

2006

SZABO P.*, POPPE A.*, FARKAS G.*, SZEKELY V.*, RENCZ M. **, COURTOIS B.
Thermal characterization and compact modeling of stacked die packages
International Conference on Thermal and Thermomechanical Phenomena in Electronic Systems (ITherm’06), San Diego, California, USA, May 30 – June 2, 2006
********
* MicRed Microelectronics Res & Dev Ltd., Hungary; ** Budapest University of Technology and Economics, Hungary;

SZABO P.*, NEMETH B.*, RENCZ M. **, COURTOIS B.
Characterization of the etching quality in micro-electro-mechanical systems by thermal transient methodology
Thermal testing and dynamic modeling of multiple die packages
International Conference on Thermal and Thermomechanical Phenomena in Electronic Systems (ITherm'06), San Diego, California, USA, May 30 – June 2, 2006

Characterization of the etching quality in micro-electro-mechanical systems by thermal transient methodology
Symposium on Design, Test, Integration and Packaging of MEMS/MOEMS (DTIP'06), Stresa, Italy, April 26-28, 2006

Thermal testing and dynamic modeling of multiple die packages
International Conference on Thermal and Thermomechanical Phenomena in Electronic Systems (ITherm'06), San Diego, California, USA, May 30 – June 2, 2006

Characterization of the etching quality in micro-electro-mechanical systems by thermal transient methodology
Symposium on Design, Test, Integration and Packaging of MEMS/MOEMS (DTIP'06), Stresa, Italy, April 26-28, 2006

Thermal modeling of multiple die packages
7th Electronics Packaging Technology Conference (EPTC'05), Singapore, December 7-9, 2005

Thermal characterization and modeling of stacked die packages
Technical Conference and Exhibition on Integration and Packaging of Micro, Nano and Electronic Systems (InterPACK 2005), San Francisco, Ca., USA, July 17-22, 2005

Thermo-mechanical characterization and integrity checking of packages and movable-structures
Nanotechnology Conference and Trade Show (NANOTECH’05), Anaheim, California, USA, May 8-12, 2005

A framework for computing transport properties of carbon nanotube-based conductance biochemical sensors
European Nano Systems (ENS’05), Paris, Rance, 14-16 December 2005

Electronic properties of graphitic surfaces with absorbed aromatic amine acids
Nanotechnology Conference and Trade Show (NanoTech’05), Anaheim, California, U.S.A.,
COURTOIS B., RENCZ M.*
Thermal modeling of multiple die packages
7th Electronics Packaging Technology Conference (EPTC'05), Singapore, December 7-9, 2005

* MicRed Microelectronics Res & Dev Ltd., Hungary